PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
UniTest Inc.	05/12/2009

RECEIVING PARTY DATA

Name:	Will Technology Co., Ltd.
Street Address:	216, Imok-dong, Jangan-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF

PROPERTY NUMBERS Total: 8

Property Type	Number
Patent Number:	6724204
Patent Number:	7285967
Patent Number:	7459399
Application Number:	11782949
Application Number:	11832770
Application Number:	11760032
Application Number:	11760022
Application Number:	11760004

CORRESPONDENCE DATA

Fax Number: (516)431-1127
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 516-431-1177
Email: tmgalgano@rcn.com
Correspondent Name: Thomas M. Galgano
Address Line 1: 20 W. Park Avenue, Suite 204
Address Line 4: Long Beach, NEW YORK 11561

ATTORNEY DOCKET NUMBER:	1834-1
NAME OF SUBMITTER:	Thomas M. Galgano
Total Attachments: 3 source=assignment#page1.tif source=assignment#page2.tif source=assignment#page3.tif	

ASSIGNMENT OF U.S. PATENTS AND PATENT APPLICATIONS

WHEREAS, UniTest Inc. (hereinafter "Assignor"), a company organized under the laws of Korea, having an address of 155-1, Hagal-dong, Giheung-gu, Yongin-city, Gyeonggi-do, KOREA is the owner of the U.S. patents and patents applications set forth in Schedule I and the inventions covered thereby (collectively "IP");

WHEREAS, Will Technology Co., Ltd. (hereinafter "Assignee"), a company organized under the laws of Korea, having an address of 216, Imok-dong, Jangan-gu, Suwon-si, Gyeonggi-do, KOREA is desirous of acquiring all right, title and interest, in and to said IP;

NOW, THEREFORE, in consideration of the sum of ten ($10.00) dollars and/or other good and valuable consideration, receipt of which is hereby acknowledged, Assignor hereby sells, assigns, and transfers to Assignee the aforesaid U.S. patents and patent applications and the inventions covered thereby set forth in Schedule I and any continuations, divisionals and reissues thereof, the same to be held and enjoyed by ASSIGNEE for its own use and enjoyment, and for the use and enjoyment of its successors, assigns, or other legal representatives, to the end of the term or terms for which the said patents are or may be granted or reissued as fully and entirely as the same would have been held and enjoyed by Assignor if this Assignment and sale had not been made; together with all claims for damages by reason of past infringement of said patents, with the right to sue for and collect the same for its own use and enjoyment, and for use and enjoyment of its successors, assigns or other legal representatives.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all letters patents of the United States on said inventions or resulting from said applications and any continuations, divisionals or reissues thereof to Assignee as assignee of the entire right, title and interest, and hereby covenants that it has full right to convey the entire right, title and interest herein assigned, and that it has not executed, and will not execute, any agreements inconsistent herewith.

UniTest Inc.

By: KIM JONG HYUN

Name:

CEO

Title:

2009. 05. 12

Date:

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SCHEDULE I

TITLE	FILED	SERIAL NO.	PUBLICATION NO./ PATENT NO. & ISSUE DATE
Probe Structure For Testing Semiconductor Devices And Method For Fabricating The Same	April 18, 2002	10/125,248	6,724,204 April 18, 2004
Probe Card Having Deeply Recessed Trench And Method For Manufacturing The Same	November 18, 2005	11/281,365	7,285,967 October 23, 2007
Method For Manufacturing Probe Structure Of Probe Card	June 6, 2007	11/756,686	7,459,399 December 2, 2008
Method For Manufacturing Probe Structure	July 25, 2007	11/782,949	US 2008/0029479
Method For Forming Bump Of Probe Card	August 2, 2007	11/832,770	US 2008/0047927
Method For Manufacturing Probe Structure Of Probe Card	June 11, 2007	11/760,032	US 2008/0190891
Method For Manufacturing Cantilever Structure Of Probe Card	June 11, 2007	11/760,022	US 2008/0190885
Method For Manufacturing Bump Of Probe Card	June 11, 2007	11/760,004	US 2008/0189942